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C. FBC MULTILAYER FERRITE CHIP BEAD

•FEATURE

- 1. SMD Bead Core for High Reliability
- 2. Suitable for power line & signal line circuit
- 3. To help you go pass the CE/FCC standard
- 4. Operating Temperature: -40 ~ +125 °C
- 5. Compliant with AEC-Q200





APPLICATION

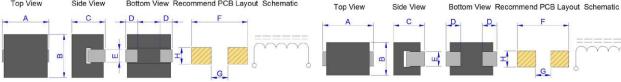
PC, IPC, Handheld Device, LowProfile Device, LCD.

ORDERING INFORMATION

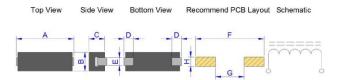
<u>FBC</u>	<u>473129</u>	<u>R</u>	<u>530</u>	<u>N</u>	<u>-35A</u>	<u>Q</u>
Series	Dimension	Material code	Impedance(Z)	Tolerance(T)	Rated Current(A)	AEC-Q
	(L*W*H)	(W, R)	(Ω) @100MHz	N=±25%		

•SHAPE AND DIMENSION

302922 TYPE Top View Side View Bottom View Recommend PCB Layout Schematic Top View Side



903028 TYPE



•SPECIFICATION Unit: mm

TYPE	Α	В	С	D	E	F	G	Н
302922	3.08+0.1/-0.15	2.90±0.10	2.20±0.10	0.80±0.20	0.85±0.10	3.70 ref.	1.10 ref.	1.10 ref
473129	4.70±0.40	3.10±0.15	2.90±0.20	1.35±0.20	1.35±0.15	4.80 ref.	1.40 ref.	1.50 ref.
903028	9.00±0.40	3.00±0.15	2.80±0.25	1.50±0.50	1.25±0.20	10.7 ref.	4.50 ref.	1.50 ref.

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•ELECTRICAL CHARACTERISTICS

Dorf Number	Impedance(Z)	Impedance(Z)	DCR (==0)	Rated Current(A)	
Part Number	(Ω) @25MHz	(Ω) @100MHz	(mΩ) Max.	ΔT=40°C	ΔT=60°C
FBC302922W400N-21A	23.0	40.0	0.6	21.0 Typ.	26.0 Typ.

^{*} N=Tolerance Code= ±25%

^{*} Rated current based on increasing product temperature: Current when temperature of the product reaches +40°C

Part Number	Impedance(Z) Impedance(Z) (Ω) (Ω)		DCR (mO)	Rated Current(A)		
Part Number	@25MHz	(12) @100MHz	(mΩ) Max.	ΔT=40°C	ΔT=60°C	
FBC473129R530N-35A	35.0	53.0	0.6	35.0 Typ.	45.0 Typ.	

^{*} N=Tolerance Code= ±25%

^{*} Rated current based on increasing product temperature: Current when temperature of the product reaches +40°C

Dorf Number	Impedance(Z)	Impedance(Z)	DCR (mO)	Rated C	urrent(A)
Part Number	(Ω) @25MHz	(Ω) @100MHz	(mΩ) Max.	ΔT=40°C	ΔT=60°C
FBC903028R101N-30A	65.0	100.0	1.0	30.0 Typ.	40.0 Typ.

^{*} N=Tolerance Code= ±25%

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^{*} Rated current based on increasing product temperature: Current when temperature of the product reaches +40°C



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C. FBC MULTILAYER FERRITE CHIP BEAD

•RELIABILITY

Test Item	Test Condition			Specification
Dimension	Actual Size	Meet Spec		
Thermal Shock (Temperature Cycle)	Temperature: -40 ~ +12 Cycle: 100 Cycles (pow	Elec. no variation Appearance no deformation		
Humidity Resistance	Humidity: 90% ~ 95% F Temperature: 60 ± 2°C		urs	Elec. no variation Appearance no deformation
High Temperature	Temperature: 125 ± 2°0 Testing Time: 96 ± 2 H			Elec. no variation Appearance no deformation
Low Temperature	Temperature: -40 ± 2°C Time: 96 ± 2 Hours	;		Elec. no variation Appearance no deformation
	Temperature	Humidity	Time	
Tomporature and	25°C	90% ~ 95% RH	3.0 Hr	Elec. no variation
Temperature and Humidity Cycle	55°C	95% ~ 96% RH	5.0 Hr	Appearance no deformation
Humaity Cycle	25°C	90% ~ 95% RH	3.0 Hr	Appearance no deformation
	Cycle: 20 Cycles			
Vibration	Frequency: 10Hz ~ 55H Direction: X, Y, Z, Time	•	1	Elec. no variation Appearance no deformation
Solderability	Go through real SMT IR-Reflow The profile like our suggest profile. Preheat: 160 ± 10°C (90 sec) Peak: 245 ± 5°C Peak Time: 50 Sec. / up 217°C			Elec. no variation Appearance no deformation
Soldering Heat Resistance	Preheat: 160 ± 10°C (90 sec) Solder: Sn / Ag / Cu (Pb Free) Solder Temp.: 260 ± 5°C, Time: 3 ± 1 seconds			Elec. no variation Appearance no deformation
Iron Solder Heat Resistance	Solder Temp.: 350 ± 5° Flux: Rosin, Time: 3 ±	Elec. no variation Appearance no deformation		
Bending Strength	Unit : m	Elec. no variation Appearance no deformation		
Flexure Strength	Unit : mm	Elec. no variation Appearance no deformation		
Terminal Strength	Mount on PCB Solder Cream (Elec. no variation Appearance no deformation		
High-Voltage	100 V DC between core	Elec. no variation Appearance no deformation		
Load life	Temperature: 25 ± 3°C Load: Allowed DC Curr	ent, Test Time: 96 ± 2	Hours	Elec. no variation Appearance no deformation

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TEST EQUIPMENT

1. HP4284A – Z ,DCR , Rated Current

OPERATING & STORAGE CONDITION

- 1. Operating Temp: -40 ~ +125°C (Including self temperature rise)
- 2. Storage Temp: -40 ~ +125°C (On Board)
- 3. Storage Life Time: 12 Month (Less than 40°C and 60% RH)

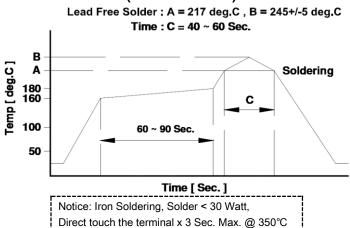
Standard Atmosphere Conditions:

Ambient Temperature 20 ± 15°C; Humidity RH 65 ± 20%

If there may be any doubt on the test result, Measurement shall be made within the following limits:

Ambient Temperature 25 ± 5°C; Humidity RH 75 ± 10%

RECOMMEND IR REFLOW CURVE (TIME: Second)



ATTENTION & CAUTION

- * Keep out of Splashing water or salt water
- * Avoid Toxic Gas (Hydrogen sulfide, Sulfurous acid, Chlorine, Ammonia)
- * Vibrations or shocks which exceed the specified condition
- * Dew condense
- * Layout near the edge of PCB
- * Over flexure after SMT mounting & PCBA
- * Pin foot or SMD pad solder ability: Pb free type is best within 6 months after delivery
- * Humidity sensitive, IPC/JEDEC J-STD-020 MSL if over Level 1, recommend bake 30mins@150°C before PCBA
- * Caution for human life relative applications: PLS contact & consult with AiT team in design stage.

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•CURVE

Fig.1 Typical Impedance vs. Frequency Curve FBC302922-Series

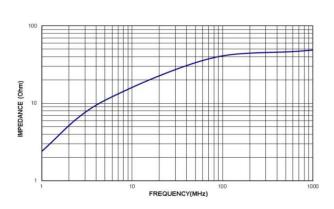


Fig.2 Typical Impedance vs. Frequency Curve FBC473129-Series

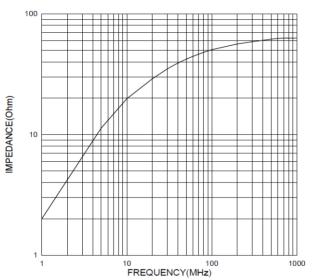
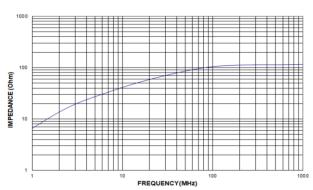


Fig.3 Typical Impedance vs. Frequency Curve FBC903028-Series



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Care Note for Use:

(1) Storage Condition:

Temperature 25 to 35°C, Humidity 45 to 60% RH

- (2) Use Temperature:
 - a. Minimum Temperature: -40°C Ambient temperature of this product.
 - b. Maximum Temperature: +125°C The value of temperature including ambient and temperature rise of this product.
 - c. Reliability test temperature range from -40 ~ +125°C
 - d. However, this is not meant as temperature grade guarantee for UL.
- (3) Model:

When this product was used in a similar or as new product to the original one, sometimes it might be unable to satisfy the specifications due to difference in condition of usage.

(4) Drop:

If this product suffered mechanical stress such as drop, characteristics may become poor (due to damage on coil / bobbin / ferrite ... etc.)

Never use such stressed product.

Care Note for Safety:

(1) Provision to Abnormal Condition:

This product itself does not have any protective function in abnormal condition such as overload, short-circuit and open-circuit conditions, etc.

Therefore, it shall be confirmed from the end product that there is no risk of smoking, fire, dielectric withstand voltage insulation resistance, etc. in abnormal conditions to provide protective devices and /or protection circuit in the end product.

(2) Temperature Rise:

Temperature rise on this product depends on the installation condition on end products.

It shall be confirmed on the actual end product that temperature rise of this product is within the specified temperature class limit.

(3) Dielectric Strength:

Dielectric withstanding test with higher voltage than specific value will damage insulating material and shorten its life.

(4) Water:

This product must not be used in wet condition resulted from water, coffee or any liquid contact because insulation strength becomes very low under such condition.

(5) Potting:

If this product is potted in some compound, coating material of magnet wire might be occasionally damaged. Please ask us if you intend to pot this product.

(6) Detergent:

Please consult AiT Semi immediately once under such circumstances because product reliability confirmation etc. is needed when this product come in contact with these chemicals.

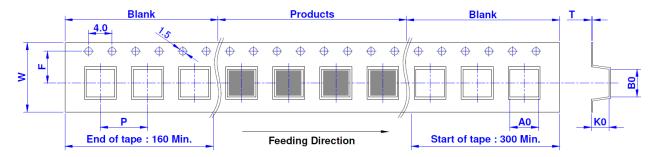
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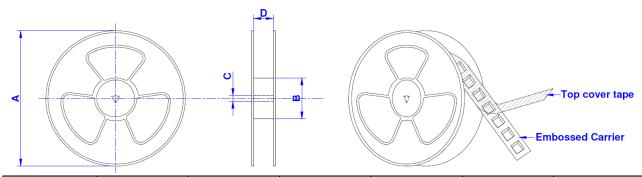
C. FBC MULTILAYER FERRITE CHIP BEAD

●TAPE DIMENSION: mm



SIZE/mm	W	Р	A0	В0	K0	Т	F
302922	12.0±0.10	8.0±0.10	3.5±0.10	3.35±0.10	2.4±0.10	0.3±0.05	5.5±0.05
473129	12.0±0.10	8.0±0.10	3.3±0.10	4.8±0.10	3.1±0.10	0.3±0.05	5.5±0.05
903028	16.0±0.10	8.0±0.10	3.25±0.10	9.25±0.10	3.05±0.10	0.35±0.05	7.5±0.05

•REEL DIMENSION: mm

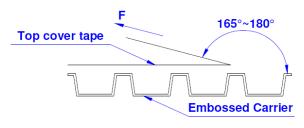


SIZE / mm	REEL SIZE	Α	В	C	D	QTY/REEL
302922	7" x 12 mm	178	60	13.5	12.5	1000 PCS
473129	7" x 12 mm	178	60	13.5	12.5	500 PCS
903028	7" x 16 mm	178	60	13.5	16.5	500 PCS

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•TEARING OFF FORCE:

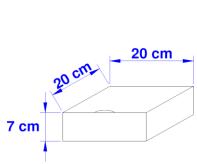


The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA - 481 - D - 2008 of 4.11stadnard).

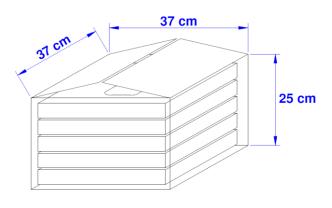
FBC

Room	Room	Room Atm.	Tearing
Temp.	Humidity		Speed
(℃)	(%)	(hPa)	(mm/min)

●BOX PACKAGE: cm







Large Box

SIZE/mm	Reels in Small Box	Small Box in Large Box
302922	4	8
473129	4	8
903028	2	8

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IMPORTANT NOTICE

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